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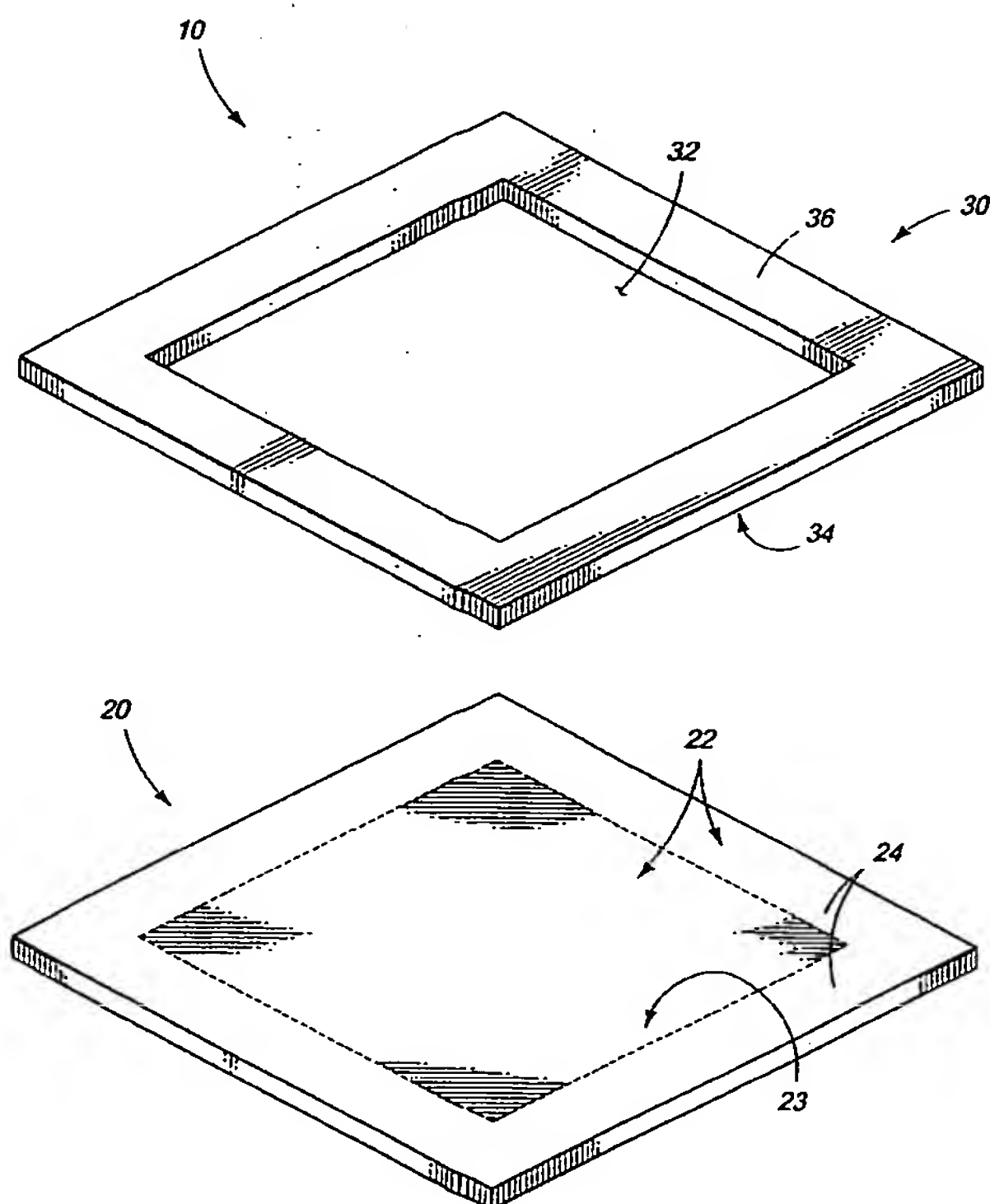
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(54) Title: HEAT SPREADER CONSTRUCTIONS, INTEGRATED CIRCUITRY, METHODS OF FORMING HEAT SPREADER CONTRUCTIONS, AND METHODS OF FORMING INTEGRATED CIRCUITRY



(57) Abstract: The invention includes a heat spreader having a base which has a perimeter surface surrounding a heat-receiving region. A frame portion interfaces the perimeter surface and has an opening traversing a thickness of the frame. The invention includes a method of forming a heat spreader construction by forming a base portion having a perimeter region surrounding a heat-receiving surface. An independent frame portion is joined to the base portion. The invention includes integrated circuitry having a heat spreader construction in thermal communication with a heat-generating device. The heat spreader has a base having a heat-receiving surface and a perimeter surface which interfaces a frame portion. The invention includes methodology for forming integrated circuitry which includes providing an integrated circuitry board having a heat generating device mounted thereon, and providing a multi-part heat spreader in thermal communication with the heat-generating device.

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